



## Description

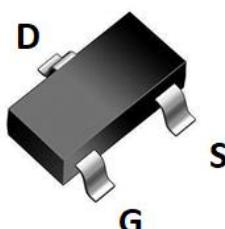
### JMT N-channel Enhancement Mode Power MOSFET

#### Features

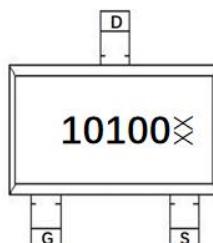
- 100V, 3A
- $R_{DS(ON)} < 120\text{m}\Omega$  @  $V_{GS} = 10\text{V}$
- $R_{DS(ON)} < 137\text{m}\Omega$  @  $V_{GS} = 4.5\text{V}$
- Advanced Trench Technology
- Provide Excellent  $R_{DS(ON)}$  and Low Gate Charge
- Lead free product is acquired

#### Application

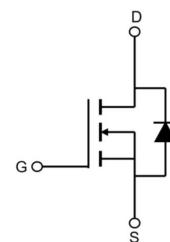
- Load Switch
- PWM Application
- Power management



SOT-23-3L top view



Marking and pin Assignment



Schematic Diagram

## Package Marking and Ordering Information

Device Marking	Device	OUTLINE	Device Package	Reel Size	Reel (PCS)	Per Carton (PCS)
10100	JMTJ11DN10A	TAPING	SOT-23-3L	7inch	3000	120000

## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter		Max.	Units
$V_{DSS}$	Drain-Source Voltage		100	V
$V_{GSS}$	Gate-Source Voltage		$\pm 20$	V
$I_D$	Continuous Drain Current	$T_A = 25^\circ\text{C}$	3	A
		$T_A = 100^\circ\text{C}$	2	A
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>		12	A
$P_D$	Power Dissipation	$T_A = 25^\circ\text{C}$	1.7	W
$R_{\theta JA}$	Thermal Resistance, Junction to Case		74	$^\circ\text{C}/\text{W}$
$T_J, T_{STG}$	Operating and Storage Temperature Range		-55 to +150	$^\circ\text{C}$

**Electrical Characteristics** ( $T_J=25^\circ\text{C}$  unless otherwise specified)

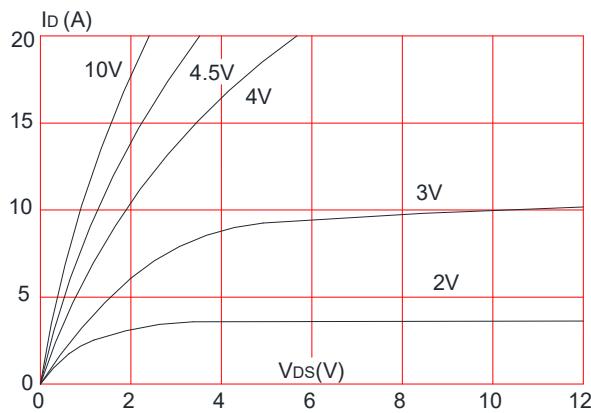
Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=250\mu\text{A}$	100	-	-	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{DS}=100\text{V}$ , $V_{GS}=0\text{V}$ ,	-	-	1.0	$\mu\text{A}$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0\text{V}$ , $V_{GS}=\pm 20\text{V}$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D=250\mu\text{A}$	1.0	1.5	2.5	V
$R_{DS(\text{on})}$ Note2	Static Drain-Source on-Resistance	$V_{GS}=10\text{V}$ , $I_D=3\text{A}$	-	92	120	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$ , $I_D=2\text{A}$	-	98	137	$\text{m}\Omega$
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=25\text{V}$ , $V_{GS}=0\text{V}$ , $f=1.0\text{MHz}$	-	765	-	pF
$C_{oss}$	Output Capacitance		-	38	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	33	-	pF
$Q_g$	Total Gate Charge	$V_{DS}=50\text{V}$ , $I_D=2\text{A}$ , $V_{GS}=10\text{V}$	-	18	-	nC
$Q_{gs}$	Gate-Source Charge		-	2.5	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	4	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=50\text{V}$ , $I_D=3\text{A}$ , $R_G=1.8\Omega$ , $V_{GS}=10\text{V}$	-	7.5	-	ns
$t_r$	Turn-on Rise Time		-	6	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	21	-	ns
$t_f$	Turn-off Fall Time		-	9	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current	-	-	3	A	
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	12	A	
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_S=3\text{A}$	-	-	1.2	V
$trr$	Body Diode Reverse Recovery Time	$I_F=3\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$	-	21	-	ns
$Qrr$	Body Diode Reverse Recovery Charge		-	22	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

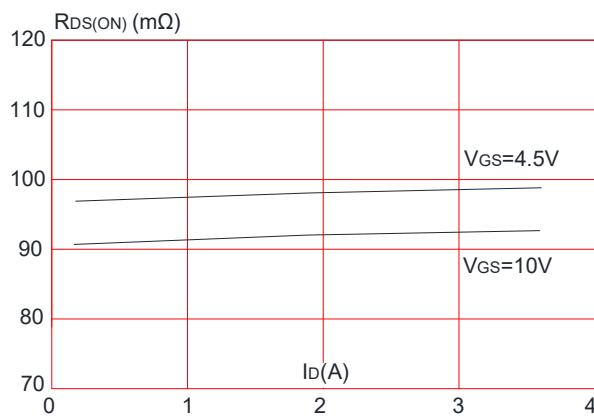
2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$ , Duty Cycle $\leq 0.5\%$

## Typical Performance Characteristics

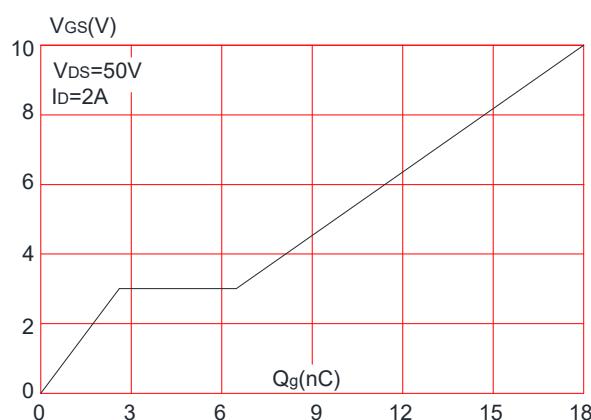
**Figure 1:** Output Characteristics



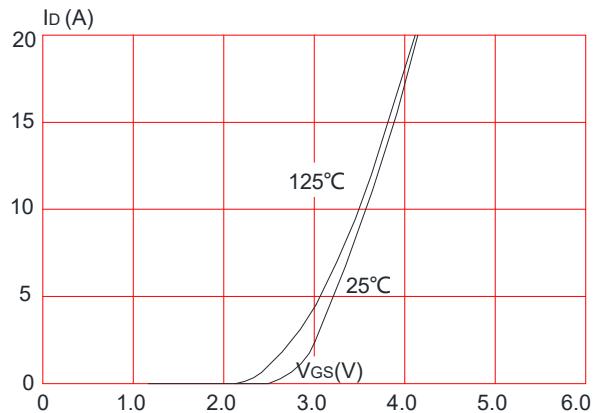
**Figure 3:** On-resistance vs. Drain Current



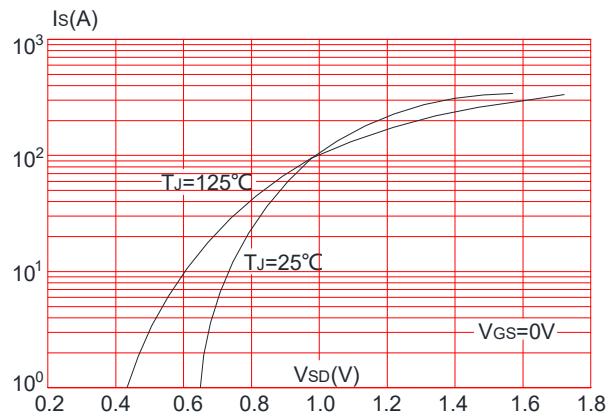
**Figure 5:** Gate Charge Characteristics



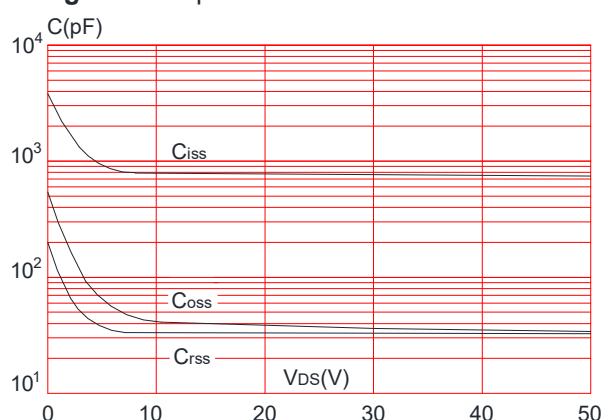
**Figure 2:** Typical Transfer Characteristics



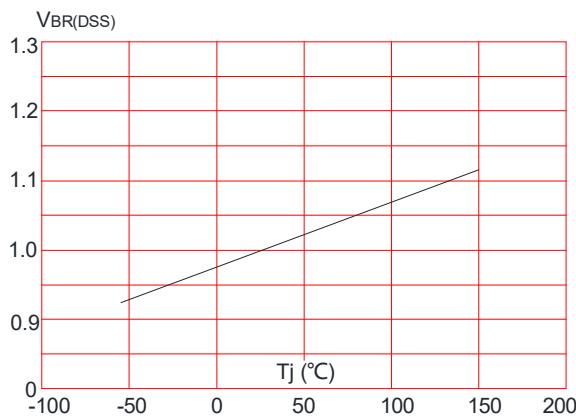
**Figure 4:** Body Diode Characteristics



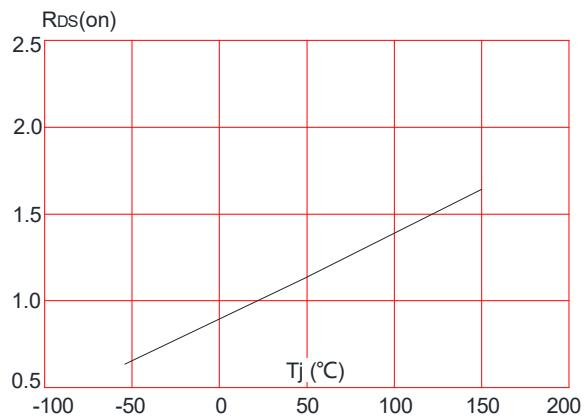
**Figure 6:** Capacitance Characteristics



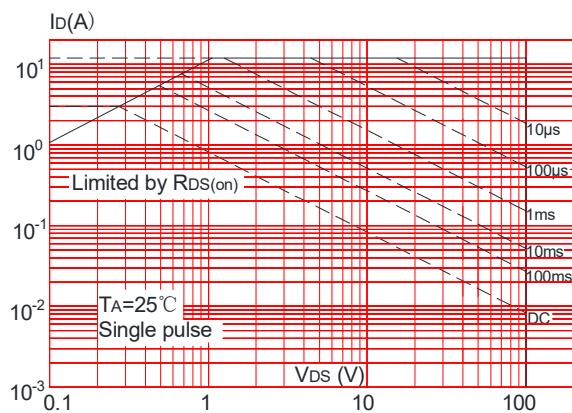
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



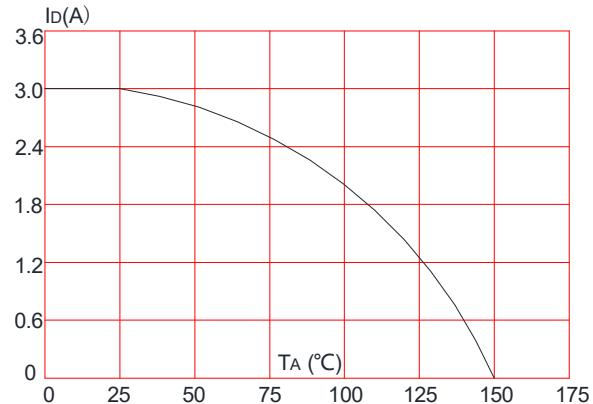
**Figure 8:** Normalized on Resistance vs. Junction Temperature



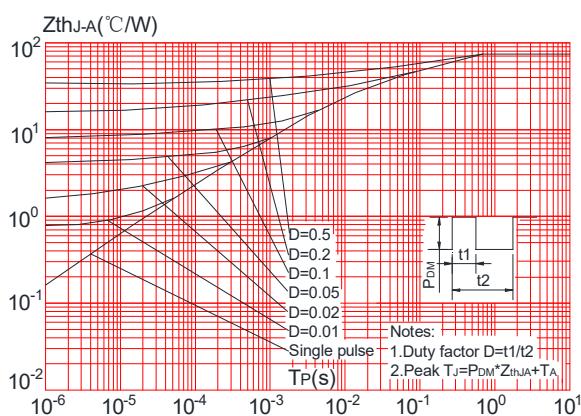
**Figure 9:** Maximum Safe Operating Area



**Figure 10:** Maximum Continuous Drain Current vs. Ambient Temperature



**Figure 11:** Maximum Effective Transient Thermal Impedance, Junction-to-Ambient



## Test Circuit

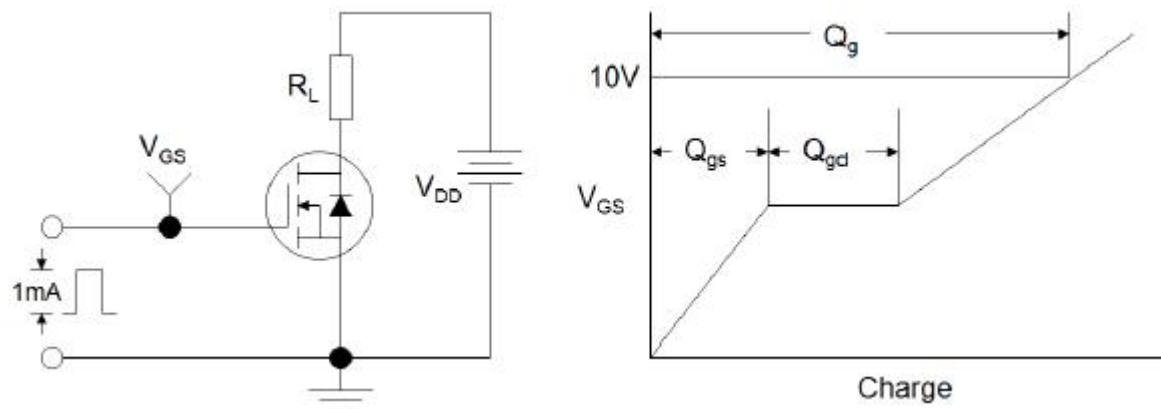


Figure 1: Gate Charge Test Circuit & Waveform

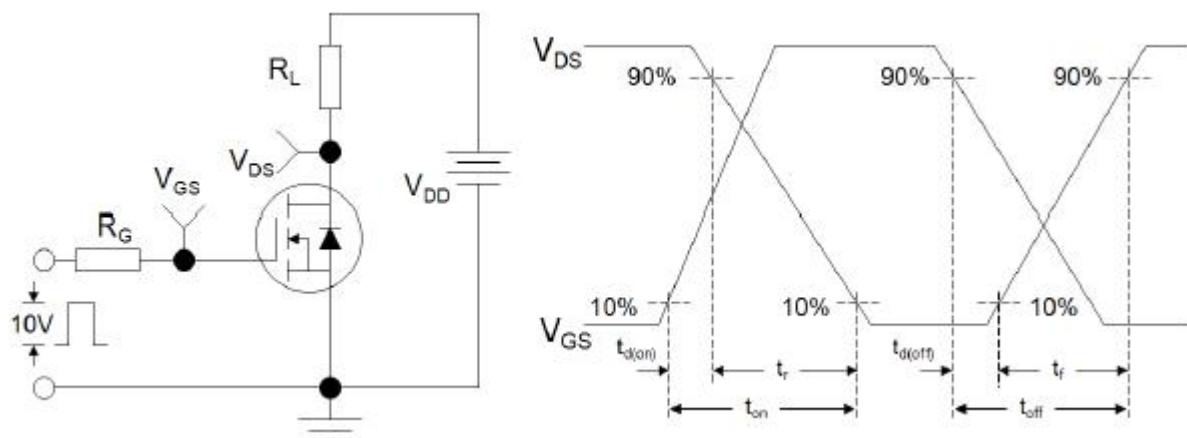


Figure 2: Resistive Switching Test Circuit & Waveforms

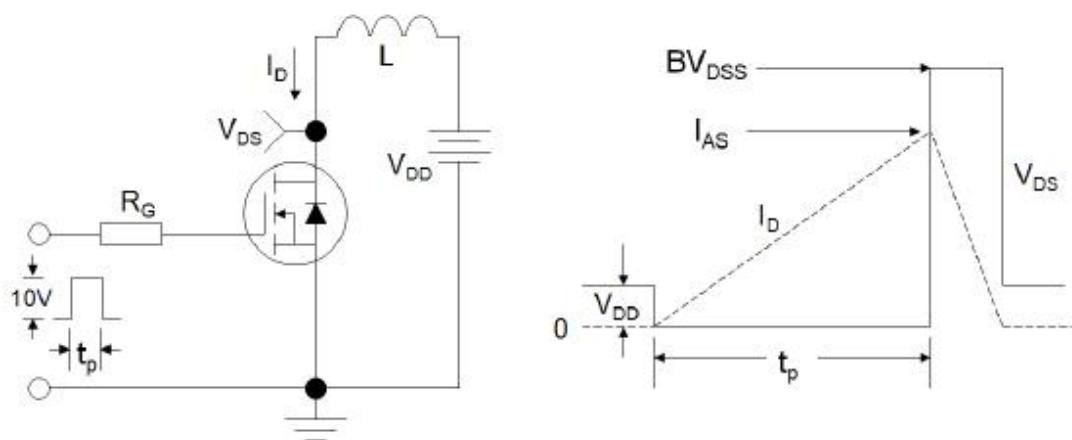
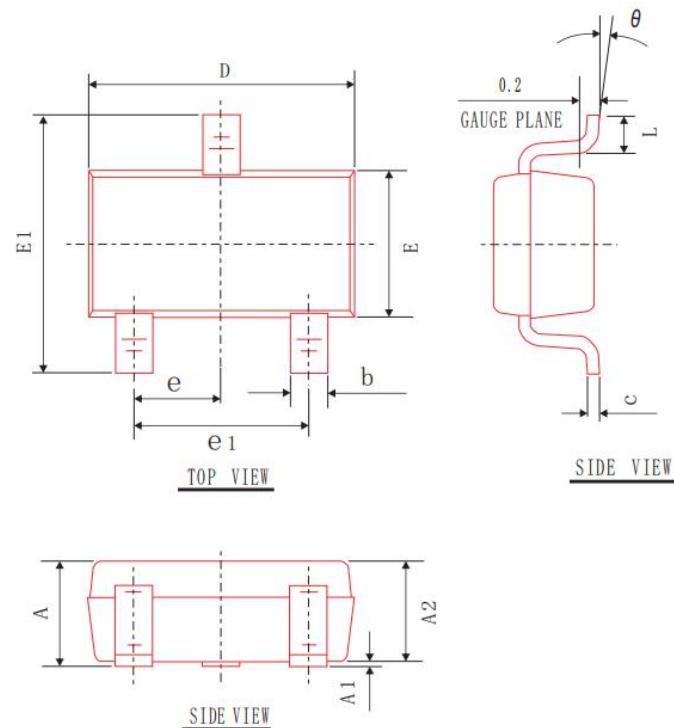


Figure 3: Unclamped Inductive Switching Test Circuit & Waveforms



## Package Mechanical Data-SOT-23-3L

COMMON DIMENSIONS  
(UNITS OF MEASURE=mm)

SYMBOL	MIN	NOM	MAX
A	—	—	1.30
A1	0.00	0.05	0.10
A2	1.00	1.10	1.20
b	0.30	0.40	0.50
c	0.119	0.127	0.135
e1	1.80	1.90	2.00
D	2.80	2.90	3.00
E	1.50	1.60	1.70
E1	2.60	2.80	3.00
L	0.30	0.45	0.60
$\theta$	0°	4°	8°
e	0.95BSC		

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